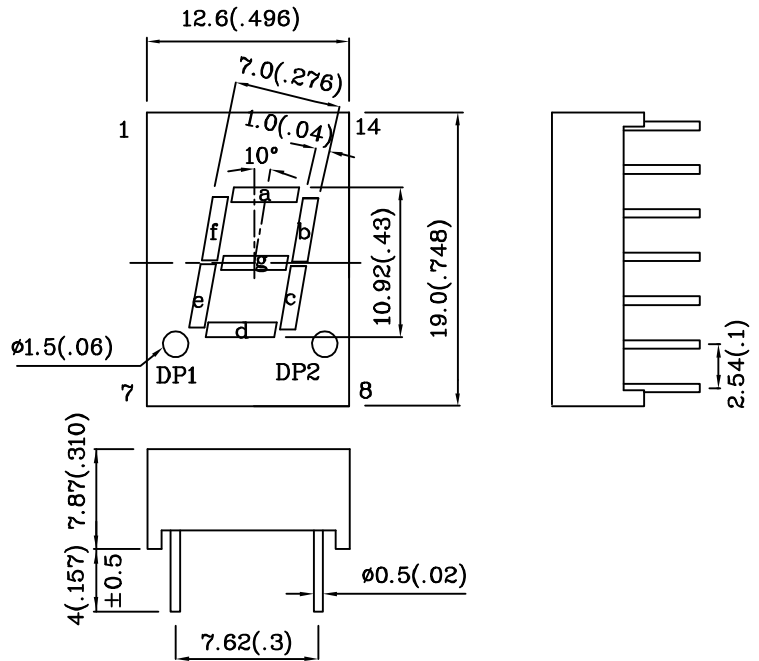
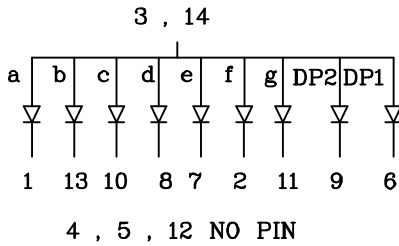


**Features**

- 0.43 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- STANDARD: GRAY FACE, WHITE SEGMENT.
- RoHS COMPLIANT.



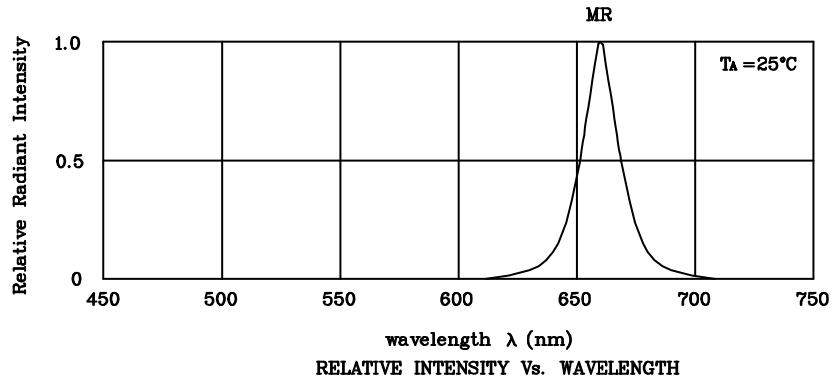
**Notes:**

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.

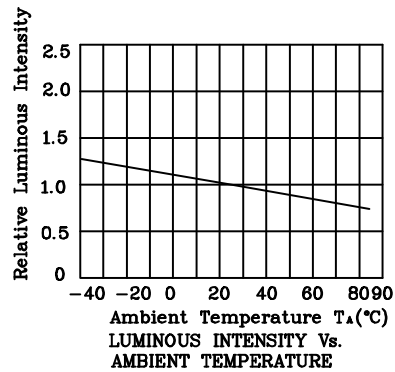
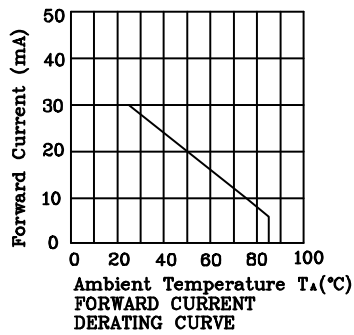
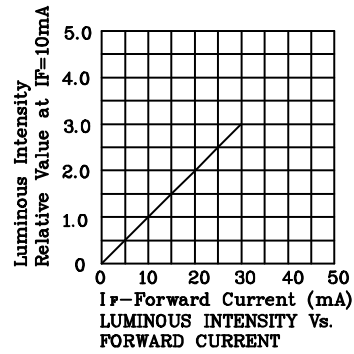
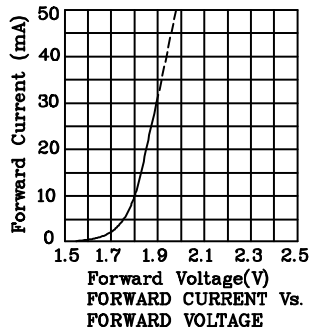
Absolute maximum ratings (TA=25°C)	MR (GaAlAs)	Unit
Reverse Voltage	V <sub>R</sub>	5 V
Forward Current	I <sub>F</sub>	30 mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	155 mA
Power Dissipation	P <sub>T</sub>	100 mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85 °C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85 °C
Lead Solder Temperature [2mm Below Package Base]	260°C For 5 Seconds	

Operating Characteristics (TA=25°C)	MR (GaAlAs)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	1.8 V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.5 V
Reverse Current (V <sub>R</sub> =5V)	I <sub>R</sub>	10 uA
Wavelength of Peak Emission (I <sub>F</sub> =10mA)	λ <sub>P</sub>	660 nm
Wavelength of Dominant Emission (I <sub>F</sub> =10mA)	λ <sub>D</sub>	640 nm
Spectral Line Full Width At Half-Maximum (I <sub>F</sub> =10mA)	Δλ	20 nm
Capacitance (V <sub>F</sub> =0V, f=1MHz)	C	45 pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (I <sub>F</sub> =10mA) ucd	Wavelength nm λ <sub>P</sub>	Description	
			min.	typ.		
XDMR11A-A	Red	GaAlAs	4700	17990	660	Common Anode, Rt. & Lt. Hand Decimal



❖ MR



Remarks:

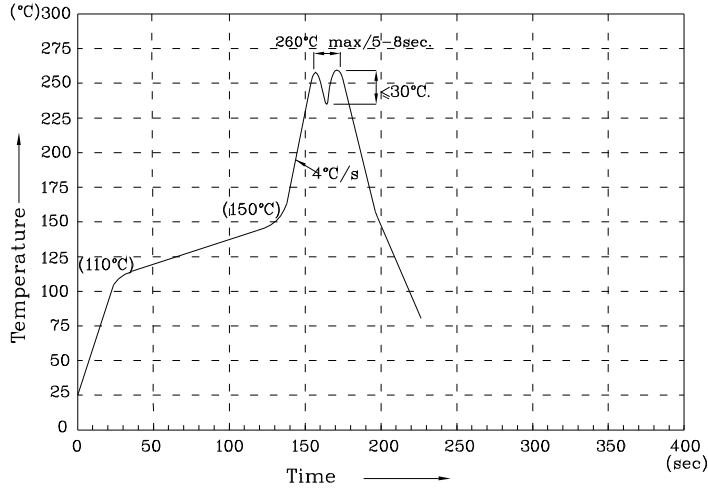
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XDMR11A-A

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.